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This listing of claims will replace all prior versions and listings of claims in the application:

## **Listing of Claims:**

Claim 1 (Previously Amended): An integrated circuit package device having a plurality of contact points, wherein the plurality of contact points includes an inner portion of said contact points and an outer portion of said contact points, the integrated circuit package device comprising at least one of the following:

- (i) a majority of power supply contacts configured substantially in an extremity of said outer portion;
- (ii) a majority of timing or frequency contacts configured substantially in said outer portion; and
- (iii) a majority of data or high speed signal contacts configured substantially in an inner side of said outer portion.

Claim 2 (Previously Amended): The integrated circuit package device according to Claim 1, wherein ground contacts are further provided along a bisectional axis through said outer portion to facilitate a ground path from outside an area of the integrated circuit package device to said inner portion.

Claim 3 (Original): The integrated circuit package device according to Claim 1, wherein said inner portion is formed substantially of ground contact points to effect a ground plane.

Claim 4 (Cancelled)

Claim 5 (Cancelled)

Claim 6 (Cancelled)

Claim 7 (Cancelled)

Claim 8 (Cancelled)

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Claim 9 (Cancelled)

Claim 10 (Previously Added): The integrated circuit package device according to claim 1 further comprising at least one ground contact configured substantially in said inner portion.

Claim 11 (Cancelled)

Claim 12 (Previously Added): The integrated circuit package device according to claim 1 wherein the inner portion and the outer portion are two distinct regions separated by a space.

Claim 13 (Previously Added): The printed circuit board according to claim 5 wherein the inner portion and the outer portion are two distinct regions separated by a space.

Claim 14 (Cancelled)

Claim 15 (Previously Added): An integrated circuit package device according to claim 1 comprising two or more of the following:

- (i) a majority of power supply contacts configured substantially in an extremity of said outer portion;
- (ii) a majority of timing or frequency contacts configured substantially in said outer portion; and
- (iii) a majority of data or high speed signal contacts configured substantially in an inner side of said outer portion.

Claim 16 (Previously Added): An integrated circuit package device according to claim 1 comprising all of the following:

- (i) a majority of power supply contacts configured substantially in an extremity of said outer portion;
- (ii) a majority of timing or frequency contacts configured substantially in said outer portion; and

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(iii) a majority of data or high speed signal contacts configured substantially in an inner side of said outer portion.

Claim 17 (Previously Added): An integrated circuit package device according to claim 15 wherein the inner portion and the outer portion are two distinct regions separated by a space.

Claim 18 (Previously Added): An integrated circuit package device according to claim 16 wherein the inner portion and the outer portion are two distinct regions separated by a space.

Claim 19 (Previously Added): An integrated circuit package device according to claim 16 and further comprising a majority of ground contacts configured substantially in said inner portion.

Claim 20 (Cancelled)

Claim 21 (Cancelled)

Claim 22 (Cancelled)

Claim 23 (Cancelled)

Claim 24 (Cancelled)

Claim 25 (Previously Added): An electrical or electronic device comprising the integrated circuit package device according to claim 15.

Claim 26 (Previously Added): An electrical or electronic device comprising the integrated circuit package device according to claim 16.

Claim 27 (Previously Added): An electrical or electronic device comprising the integrated circuit package device according to claim 17.